

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPG20N04S4-08A	**Issued**	11. August 2021
MA#	MA005556836		
Package	PG-TDSON-8-10	**Weight***	100.34 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.592	1.59	1.59	15865	15865
chip_2	inorganic material	silicon	7440-21-3	1.592	1.59	1.59	15865	15865
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		131	
	non noble metal	iron	7439-89-6	0.044	0.04		436	
	non noble metal	copper	7440-50-8	43.681	43.53	43.58	435334	435901
wire	non noble metal	aluminium	7429-90-5	0.828	0.83	0.83	8252	8252
encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		885	
	plastics	epoxy resin	-	6.305	6.28		62834	
	inorganic material	silicondioxide	60676-86-0	38.006	37.88	44.25	378771	442490
leadfinish	non noble metal	tin	7440-31-5	1.396	1.39	1.39	13917	13917
plating	inorganic material	phosphorus	7723-14-0	0.001			14	
	non noble metal	nickel	7440-02-0	0.603	0.60	0.60	6010	6024
solder	non noble metal	tin	7440-31-5	0.070	0.07		695	
	noble metal	silver	7440-22-4	0.087	0.09		869	
	non noble metal	lead	7439-92-1	3.330	3.32	3.48	33190	34754
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			27	
	non noble metal	copper	7440-50-8	2.699	2.69	2.69	26897	26932
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com